ASM

The Best Choice of Your Career

WWW.ASMPACIFIC.COM
Agenda of Recruitment Talk

- Company Profile
- Our Products & Solutions
- Career Prospects
- Vacancies, Benefits & Application Method
Company Profile of ASMPT

- Public Listed Company in Hong Kong since January 1989
- Headcount in the world > 15,000 (as of Dec 31, 2014)
- R&D / Manufacturing Area
  - Hong Kong Plant – 280,000 sq. feet
  10 floors in Watson Centre, Kwai Chung
ASMPT History

1975
- ASMPT Founded

1989
- Listed on the HK Stock Exchanges
- Established 1st China Plant in Shenzhen

1990
- Extended R&D center to Singapore

2000
- 2003
- Expanded production capacity to Malaysia
- Expanded production capacity to Fuyong, China

2008
- Expanded production capacity to Huizhou, China
- Launched R&D center in Chengdu, China

2010
- Expanded production capacity to Longgang, China

2011
- 2013
- 2014
- Acquired Siemens Electronics Assembly System (SEAS) Business & formed ASM AS in Germany
- Acquired DEK in United Kingdom
- Set up Advanced Laser Technology Centre (ASM ALSI) in the Netherlands

2015年5月29日
ASM PT Around The World

ASM Pacific Technology (ASMPT)

China
- Hong Kong
- Shenzhen (Bao’an)
- Shenzhen (Yantian)
- Shenzhen (Longgang)
- Huizhou
- Fuyong
- Chengdu

Malaysia
- Pasir Gudang

Singapore
- Yishun
- Jurong
- Commonwealth

The Netherlands
- Beuningen

Germany
- Munich

United Kingdom
- Weymouth

Die Bonder
Flip Chip Bonder
TCB Bonder
COG Bonder
Al Wire Bonder
Trim Form Equipment
Ball Placement
Test / Finishing
Handlers
Jig Saw
R & D Center

WB Fabricated Parts & Sub-assemblies
SMT Fabricated Parts & Sub-assemblies
FOL Fabricated Parts & Sub-assemblies
Stamped & Etched Lead Frames
EOL Fabricated Parts & Sub-assemblies

R & D Center

Fabricated Parts
Sub-assemblies
Lead Frame Plating
Feeder Production
SMT Sub-assemblies

SMT Placement
R & D Center

Etched Lead Frames
SMT Printing

Laser Dicing
R & D Center

SMT Placement
Alternate Energy
R & D Center

Cu/Au/Ag Wire Bonders
Stud Bumping
Automolding Systems
In-Line System
Solar Equipment
R & D Center

SMT Printing
Software Solutions
Service Solutions
R & D Center
World’s No. 1 in Semiconductor Assembly Equipment Industry
Customer and Industry Recognition for ASMPT

ASE
ASE
Continental
Flextronics
Pepperl+Fuchs
Solar Awards 2014

VLSResearch
THE BEST
SUPPLIERS
Customer Satisfaction 2014

VLSResearch
10 BEST
SUPPLIERS
Customer Satisfaction 2014

CaringCompany
2012-14

FinanceAsia
ASIA’S
BEST
COMPANIES
2014
BEST SMALL CAP – HONG KONG
Great People Around the World Inspired to Deliver Innovative Solutions!

ASMPT Global R&D Network
(>1460 R&D Engineers > 1100 Patents > 430 Patents in Process)
Our Products & Solutions
Inside a Smartphone
Semiconductor Manufacturing Assembly Process

- Wafer
- Die Bonding
- Wire Bonding
- Molding
- Singulation
- Trim & Form / Ball Placement
- Testing / Finishing
- IC, LED, Electronics
Compact Flash Card

IC Die Bonder

2 Dies Stacked
Multi-Die Stacked
4 Dies Stacked

High Capacity Memory Cards
CPU / Memory Manufacturing Solution (IC / Flip Chip Packaging)

ISLinDA
Automatic 12” Die Bonder

AD9212
Automatic Flip Chip Bonder

TwinEagle Xtreme
Dual Bondhead Gold Ball Wire Bonder

Gameplay using Wii Controller and Wii Remote Plus controls together
LED General Lighting / Decorative Lighting

- **AD220**
  Automatic eutectic die bonder

- **AD211**
  Automatic eutectic die bonder

- **AD830LB**
  Automatic Die Bonder (LED Light Bar)

- **PS410**
  Automatic LED Sorter

**LED Lighting**
3D Display / Touch Panel Solution

GEMINI
Automatic Panel Bonding System

Chip on Glass + Flex on Glass Solution
In-line System

Intelligent Dynamic Efficient Assembly Line
Career Prospects
Various Engineering Posts

- ASM provides jobs covering various engineering disciplines
  - Mechanical / Mechatronics Engineering (ME)
  - Electronics / Electrical Engineering (EE)
  - Computer Engineering (CE)
  - Computer Science (CS)
  - Industrial Engineering (IE)
  - Physics Science (PS)
  - Material Science (MS)
  - Chemical Engineering (Chem)
  - Civil Engineering (Civil)
  - …
# R&D and Product Groups

- **Product Development**

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<thead>
<tr>
<th>Discipline</th>
<th>Product Team</th>
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<tbody>
<tr>
<td></td>
<td>Mechanical Design</td>
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<tr>
<td>Mechanical / Mechatronics Engineering</td>
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<tr>
<td>Electronics / Electrical Engineering</td>
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<tr>
<td>Computer Engineering</td>
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<tr>
<td>Industrial Engineering</td>
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<tr>
<td>Computer Science</td>
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## Technology Development

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<tr>
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Vacancies, Benefits & Application Method
Integration of world wide experts

- ~64% with qualification of Master’s Degree or above
- Some of them are double Master’s Degree holders

- Bachelor's Degree 29.7%
- Master's Degree 56.37%
- Others 6.14%
- Doctoral Degree 7.79%
## Current R&D and Marketing Vacancies

<table>
<thead>
<tr>
<th>Fields</th>
<th>Positions</th>
</tr>
</thead>
</table>
| **Research & Development** | □ Mechanical Engineers  
□ Software Engineers  
□ Electronic Engineers  
□ Process Engineers  
□ Computer Vision Engineers  
□ Vibration Engineers  
□ Reliability Engineers  
□ Control Engineers  
□ CAE Engineers |
| **Marketing**     | □ Customer Services Engineers  
□ Sales Engineers |
Requirements

Bachelor’s Degree or above in Engineering, Science or relevant disciplines

Keen interest and passion in seeking technology & product development as your long term career

Self-motivated, innovative & devoted
Good interpersonal, reasoning and analytical

Good command of English and Chinese (knowledge of Mandarin is a plus)

Please refer to our company website for specific requirements of positions
Employment Conditions (Fringe Benefits)

From Monday to Friday with 5-Day working week (R&D / Marketing) (Flexible working hours system)

- Annual Leave: 12 days / annum (Max 16 days)
- Statutory Holidays

Medical Scheme & MPF

Education Subsidy (HK$35,000 / year for Part-time evening Master’s Degree Programmes)

Flexi Benefits Scheme
Vision Care, Dental Care, Medical Claim Top-Up, Personal Medical Insurance, Medical Check-up
Chinese New Year Bonus (One-month basic salary)

Around up to 1.2 months’ basic salary in 2012 (By Performance)
Around up to 1.0 month’s basic salary in 2013 (By Performance)

Bonus Schemes:
Performance Gratuity Scheme (PGS) for E1 Engineers
Profit Sharing Scheme (PSS) for Senior Engineers
Application Method

- Interested applicants please apply via our company website:

- Address: 12/F, Watson Centre, 16-22 Kung Yip Street, Kwai Chung, New Territories, Hong Kong
- Tel: 852-2619 2000
- Fax: 852-2619 2107
- Email: inquire@asmpt.com

- For more corporate information, please visit: www.asmpacific.com